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Attorney Docket No.: 10664-166001

Mail Stop Patent Application

July 18, 2003

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Presented for filing is a new original patent application of:

Applicant: GARY G. LIU

BOSTON DALLAS Title:

SPAM PROCESSING SYSTEM AND METHODS INCLUDING

SHARED INFORMATION AMONG PLURAL SPAM FILTERS

DELAWARE

NEW YORK

SAN DIEGO

SILICON VALLEY

TWIN CITIES

WASHINGTON, DC

Enclosed are the following papers, including those required to receive a filing date under 37 CFR §1.53(b):

	Pages
Specification	38
Claims	9
Abstract	1
Declaration	1 (unsigned)
Dungarin a(a)	0

Drawing(s) 9

Enclosures:

- Declaration and Power of Attorney by Assignee (unsigned); and Postcard.
- Request for Non-Publication

Under 37 CFR §1.53(f), no filing fee is being paid at this time.

If this application is found to be incomplete, or if a telephone conference would otherwise be helpful, please call the undersigned at (650) 839-5070.

Kindly acknowledge receipt of this application by returning the enclosed postcard.

Please direct all correspondence to the following:

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Commissioner for Patents July 18, 2003 Page 2

Please direct all correspondence to the following:

26181

PTO Customer Number

Respectfully submitted,

Mark D. Kirkland Reg. No. 40,048

Enclosures

MDK/ljj 50164897.doc

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REQUEST AND CERTIFICATION UNDER 35 U.S.C. 122(b)(2)(B)(i)

First N	lamed Inventor	Gary G. Liu
Title SPAM Proces Including Sha SPAM Filters		ssing System And Methods ared Information Among Plural
Atty Do	ocket Number	10664-166001

I hereby certify that the invention disclosed in the attached application has not and will not be the subject of an application filed in another country, or under a multilateral agreement, that requires publication at eighteen months after filing. I hereby request that the attached application not be published under 35 U.S.C. 122(b).

July 18, 2003

Date

Signature

Mark D. Kirkland, Reg. No. 40,048

Typed or printed name

This request must be signed in compliance with 37 CFR 1.33(b) and submitted with the application **upon filing**.

Applicant may rescind this nonpublication request at any time. If applicant rescinds a request that an application not be published under 35 U.S.C. 122(b), the application will be scheduled for publication at eighteen months from the earliest claimed filing date for which a benefit is claimed.

If applicant subsequently files an application directed to the invention disclosed in the attached application in another country, or under a multilateral international agreement, that requires publication of applications eighteen months after filing, the applicant **must** notify the United States Patent and Trademark Office of such filing within forty-five (45) days after the date of the filing of such foreign or international application. **Failure to do so will result in abandonment of this application (35 U.S.C. 122(b)(2)(B)(iii)).**

Burden Hour Statement: This collection of information is required by 37 CFR 1.213(a). The information is used by the public to request that an application not be published under 35 U.S.C. 122(b) (and the PTO to process that request). Confidentiality is governed by 35 U.S.C. 122 and 37 CFR 1.14. This form is estimated to take 6 minutes to complete. This time will vary depending upon the needs of the individual case. Any comments on the amount of time you are required to completed this form should be sent to the Chief Information Officer, U.S. Patent and Trademark Office, Washington, DC 20231. DO NOT SEND FEES OR COMPLETED FORMS TO THIS ADDRESS. SEND TO: Assistant Commissioner for Patents, Washington, DC 20231.